

# SN54ALS109A, SN54AS109A, SN74ALS109A, SN74AS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

SDAS198B – APRIL 1982 – REVISED AUGUST 1995

- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

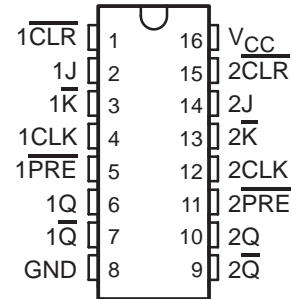
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS109A	50	6
'AS109A	129	29

## description

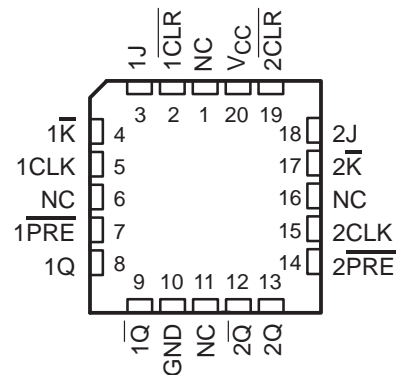
These devices contain two independent J-K positive-edge-triggered flip-flops. A low level at the preset ( $\overline{PRE}$ ) or clear ( $\overline{CLR}$ ) inputs sets or resets the outputs regardless of the levels of the other inputs. When  $\overline{PRE}$  and  $\overline{CLR}$  are inactive (high), data at the J and  $\overline{K}$  inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the J and  $\overline{K}$  inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding  $\overline{K}$  and tying J high. They also can perform as D-type flip-flops if J and  $\overline{K}$  are tied together.

The SN54ALS109A and SN54AS109A are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74ALS109A and SN74AS109A are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54ALS109A, SN54AS109A . . . J PACKAGE  
SN74ALS109A, SN74AS109A . . . D OR N PACKAGE  
(TOP VIEW)



SN54ALS109A, SN54AS109A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

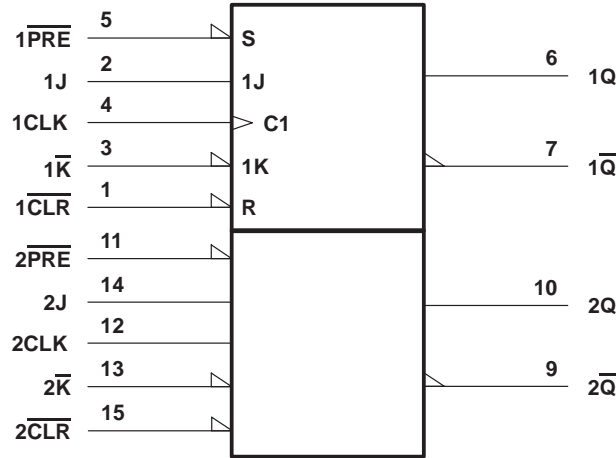
INPUTS					OUTPUTS	
$\overline{PRE}$	$\overline{CLR}$	CLK	J	$\overline{K}$	Q	$\overline{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H <sup>†</sup>	H <sup>†</sup>
H	H	↑	L	L	L	H
H	H	↑	H	L	Toggle	
H	H	↑	L	H	Q0	$\overline{Q}0$
H	H	↑	H	H	H	L
H	H	L	X	X	Q0	$\overline{Q}0$

<sup>†</sup> The output levels in this configuration are not specified to meet the minimum levels for  $V_{OH}$  if the lows at  $\overline{PRE}$  and  $\overline{CLR}$  are near  $V_{IL}$  maximum. Furthermore, this configuration is nonstable; that is, it does not persist when either  $\overline{PRE}$  or  $\overline{CLR}$  returns to its inactive (high) level.

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## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.  
Pin numbers shown are for the D, J, and N packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Operating free-air temperature range, $T_A$ : SN54ALS109A	-55°C to 125°C
SN74ALS109A	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions

		SN54ALS109A			SN74ALS109A			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX			
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V		
$V_{IH}$	High-level input voltage	2			2			V		
$V_{IL}$	Low-level input voltage			0.7			0.8	V		
$I_{OH}$	High-level output current			-0.4			-0.4	mA		
$I_{OL}$	Low-level output current			4			8	mA		
$f_{clock}$	Clock frequency	0		30	0		34	MHz		
$t_w$	Pulse duration	PRE or CLR low		15			15	ns		
		CLK high		16.5			14.5			
		CLK low		16.5			14.5			
$t_{su}$	Setup time before CLK↑	Data		15			15	ns		
		PRE or CLR inactive		10			10			
$t_h$	Hold time after CLK↑	Data		0			0	ns		
$T_A$	Operating free-air temperature			-55		125		0	70	°C



# SN54ALS109A, SN54AS109A, SN74ALS109A, SN74AS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS109A		SN74ALS109A		UNIT		
		MIN	TYP†	MAX	MIN		TYP†	MAX
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.5		-1.5	V	
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $I_{OH} = -0.4\text{ mA}$	$V_{CC}-2$			$V_{CC}-2$		V	
$V_{OL}$	$V_{CC} = 4.5\text{ V}$			0.25	0.4	0.25	0.4	V
						0.35	0.5	
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = 7\text{ V}$	CLK, J, or $\overline{K}$				0.1	0.1	mA
		$\overline{PRE}$ or $\overline{CLR}$				0.2	0.2	
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 2.7\text{ V}$	CLK, J, or $\overline{K}$				20	20	$\mu\text{A}$
		$\overline{PRE}$ or $\overline{CLR}$				40	40	
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0.4\text{ V}$	CLK, J, or $\overline{K}$				-0.2	-0.2	mA
		$\overline{PRE}$ or $\overline{CLR}$				-0.4	-0.4	
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.25\text{ V}$	-20		-112	-30		-112	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$ , See Note 1		2.4	4		2.4	4	mA

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

NOTE 1:  $I_{CC}$  is measured with J,  $\overline{K}$ , CLK, and  $\overline{PRE}$  grounded, then with J, K, CLK, and  $\overline{CLR}$  grounded.

## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_L = 500\ \Omega$ , $T_A = \text{MIN to MAX}\S$				UNIT
			SN54ALS109A		SN74ALS109A		
			MIN	MAX	MIN	MAX	
$f_{\text{max}}$			30		34		MHz
$t_{\text{PLH}}$	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	3	17	3	13	ns
$t_{\text{PHL}}$			5	17	5	15	
$t_{\text{PLH}}$	CLK	Q or $\overline{Q}$	5	21	5	16	ns
$t_{\text{PHL}}$			5	20	5	18	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



# SN54ALS109A, SN54AS109A, SN74ALS109A, SN74AS109A

## DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Operating free-air temperature range, $T_A$ : SN54AS109A	-55°C to 125°C
SN74AS109A	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		SN54AS109A			SN74AS109A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.8			0.8	V
$I_{OH}$	High-level output current			-2			-2	mA
$I_{OL}$	Low-level output current			20			20	mA
$f_{clock}^*$	Clock frequency	0		90	0		105	MHz
$t_w^*$	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low		4		4		ns
		CLK high		4		4		
		CLK low		5.5		5.5		
$t_{su}^*$	Setup time before CLK↑	Data		5.5		5.5	ns	
		$\overline{PRE}$ or $\overline{CLR}$ inactive		2		2		
$t_h^*$	Hold time after CLK↑	Data		0		0	ns	
$T_A$	Operating free-air temperature	-55		125	0		70	°C

\* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS109A			SN74AS109A			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$	$V_{CC} = 4.5 V$ , $I_I = -18 mA$			-1.2			-1.2	V
$V_{OH}$	$V_{CC} = 4.5 V$ to $5.5 V$ , $I_{OH} = -2 mA$	$V_{CC}-2$			$V_{CC}-2$			V
$V_{OL}$	$V_{CC} = 4.5 V$ , $I_{OL} = 20 mA$		0.25	0.5		0.25	0.5	V
$I_I$	$V_{CC} = 5.5 V$ , $V_I = 7 V$			0.1			0.1	mA
$I_{IH}$	CLK, J, or $\overline{K}$			20			20	$\mu A$
	$\overline{PRE}$ or $\overline{CLR}$	$V_{CC} = 5.5 V$ , $V_I = 2.7 V$		40			40	
$I_{IL}$	CLK, J, or $\overline{K}$			-0.5			-0.5	mA
	$\overline{PRE}$ or $\overline{CLR}$	$V_{CC} = 5.5 V$ , $V_I = 0.4 V$		-1.8			-1.8	
$I_{O}^{\S}$	$V_{CC} = 5.5 V$ , $V_O = 2.25 V$	-30		-112	-30		-112	mA
$I_{CC}$	$V_{CC} = 5.5 V$ , See Note 1		11.5	17		11.5	17	mA

‡ All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^\circ C$ .

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

NOTE 1:  $I_{CC}$  is measured with J, K, CLK, and PRE grounded, then with J, K, CLK, and CLR grounded.



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## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54AS109A		SN74AS109A		
			MIN	MAX	MIN	MAX	
f <sub>max</sub> *			90		105		MHz
t <sub>PLH</sub>	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$	2	9	2	8	ns
t <sub>PHL</sub>			3.5	11.5	3.5	10.5	
t <sub>PLH</sub>	CLK	Q or $\overline{\text{Q}}$	2.5	10	2.5	9	ns
t <sub>PHL</sub>			3.5	10.5	3.5	9	

\* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

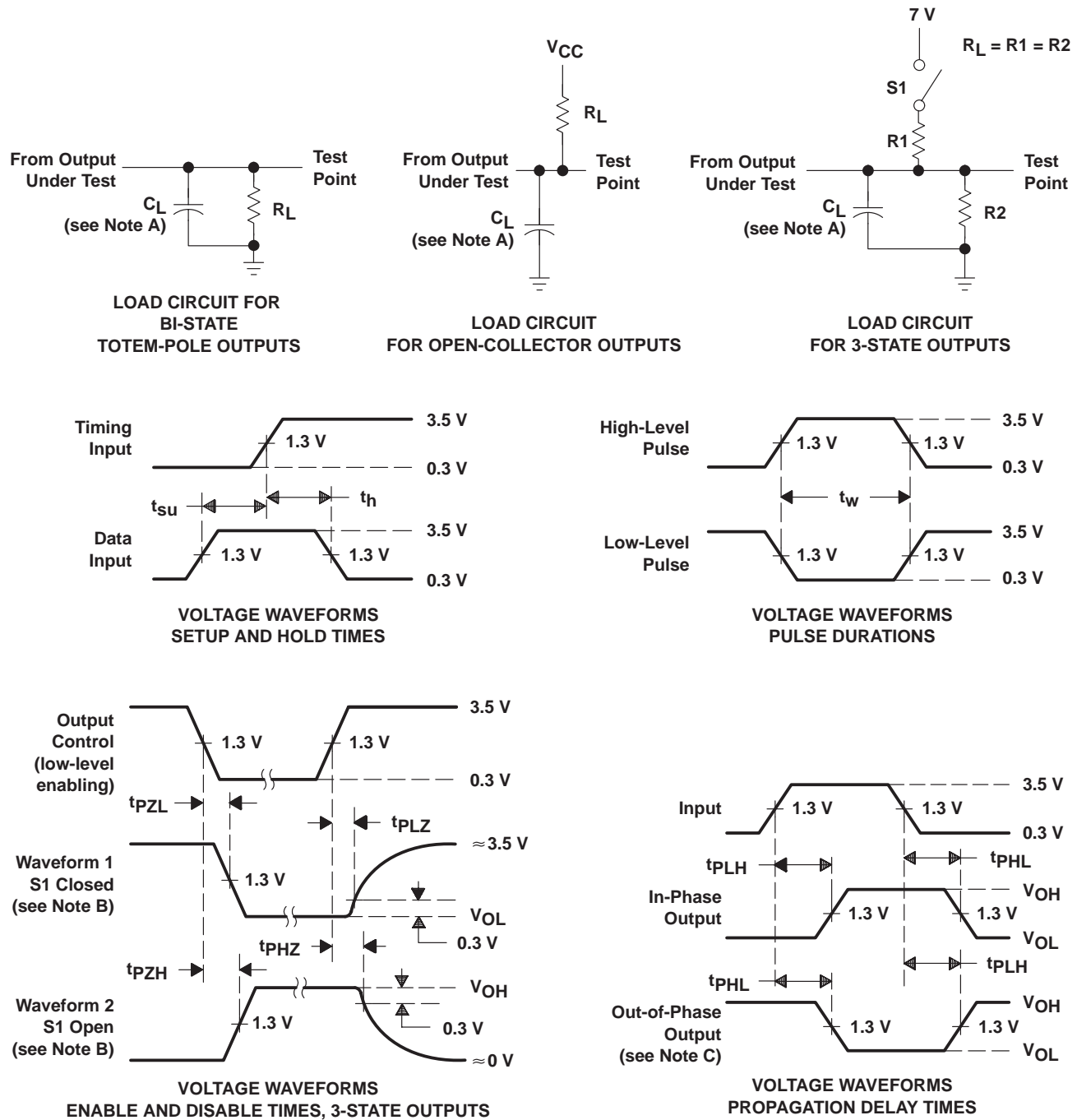
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



# SN54ALS109A, SN54AS109A, SN74ALS109A, SN74AS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

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## PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
84000012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8400001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
8400001FA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	
JM38510/37102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/37102BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/37102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/37102BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54ALS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74ALS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74ALS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS109ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74AS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS109ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54AS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN54ALS109A, SN54AS109A, SN74ALS109A, SN74AS109A :**

- Catalog: [SN74ALS109A](#), [SN74AS109A](#)
- Military: [SN54ALS109A](#), [SN54AS109A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS109ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



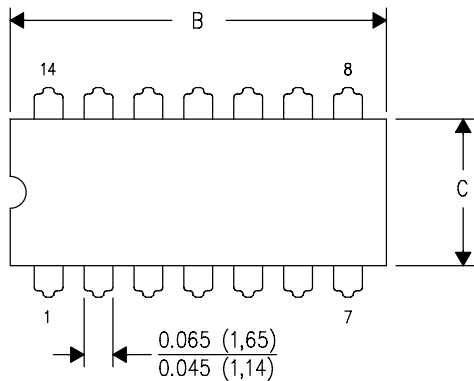
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS109ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS109ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS109ANSR	SO	NS	16	2000	367.0	367.0	38.0

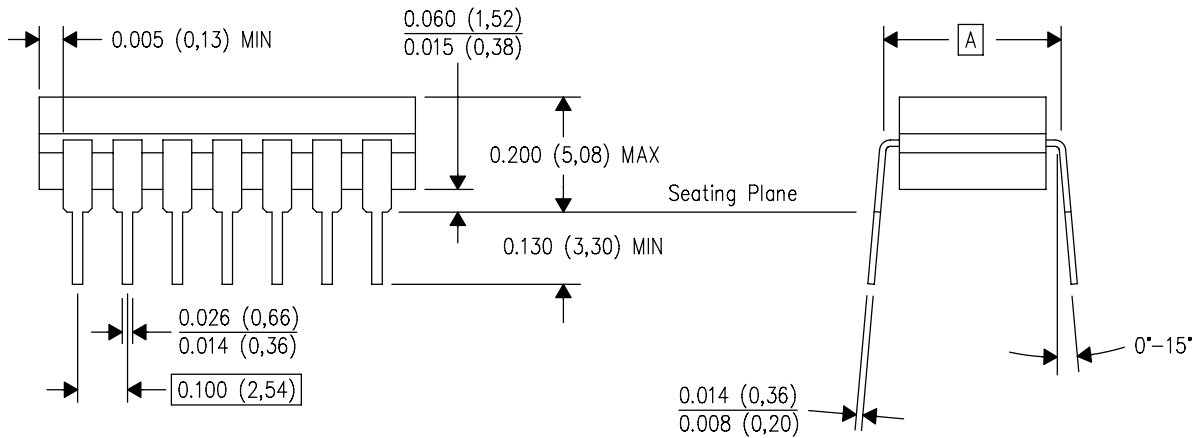
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

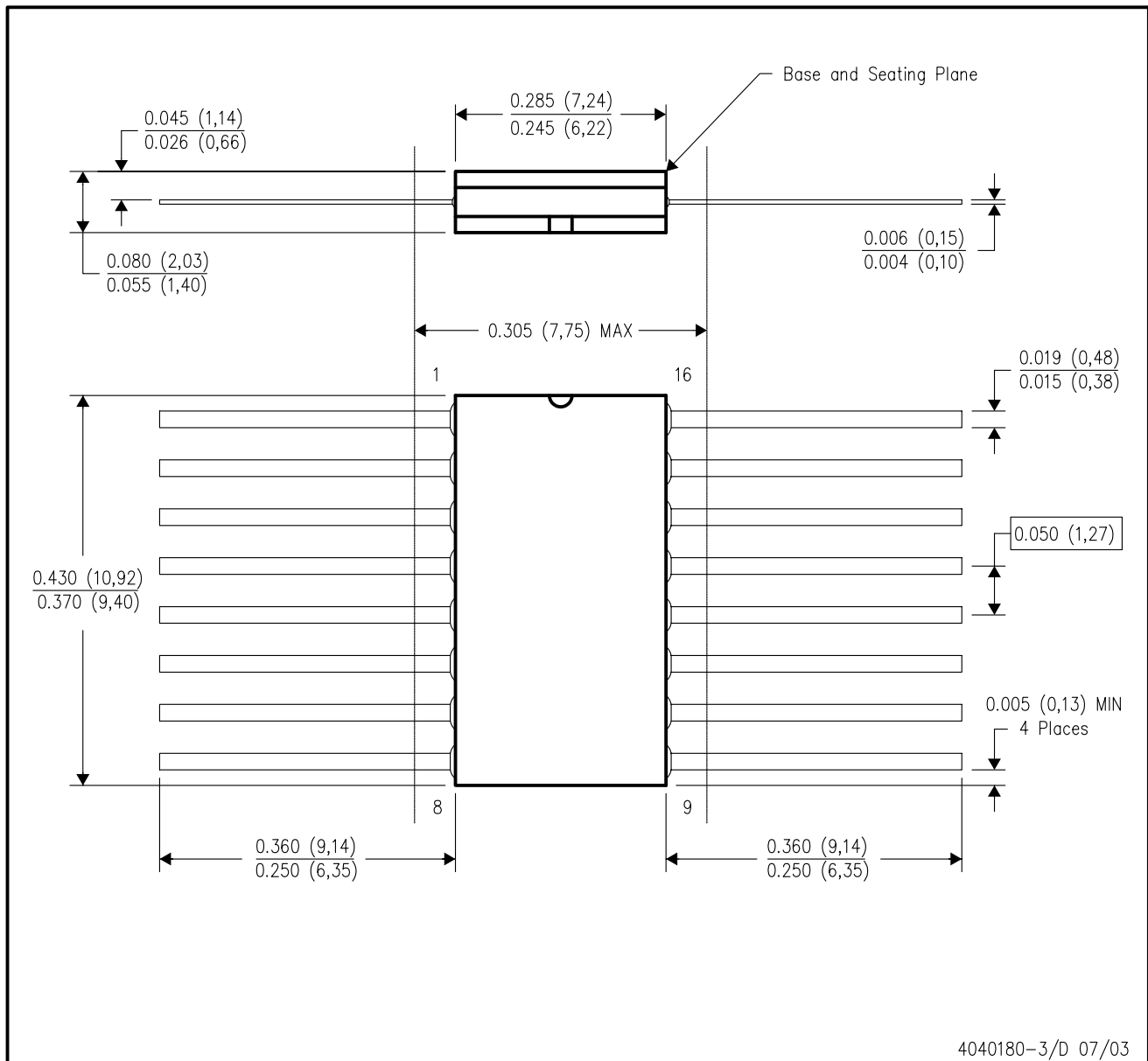


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

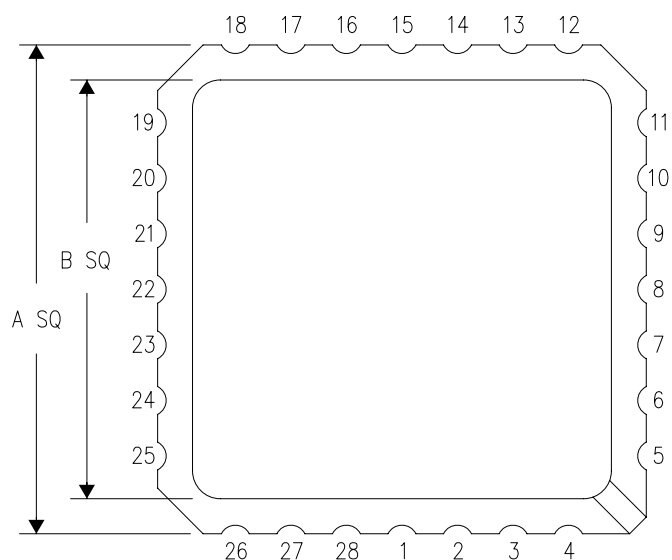


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

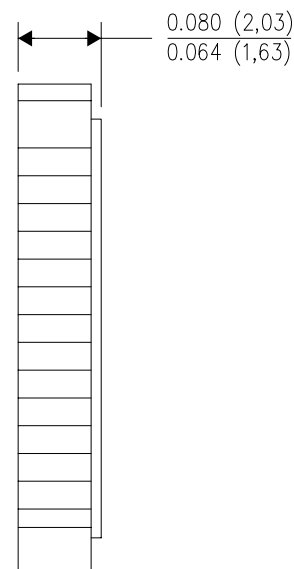
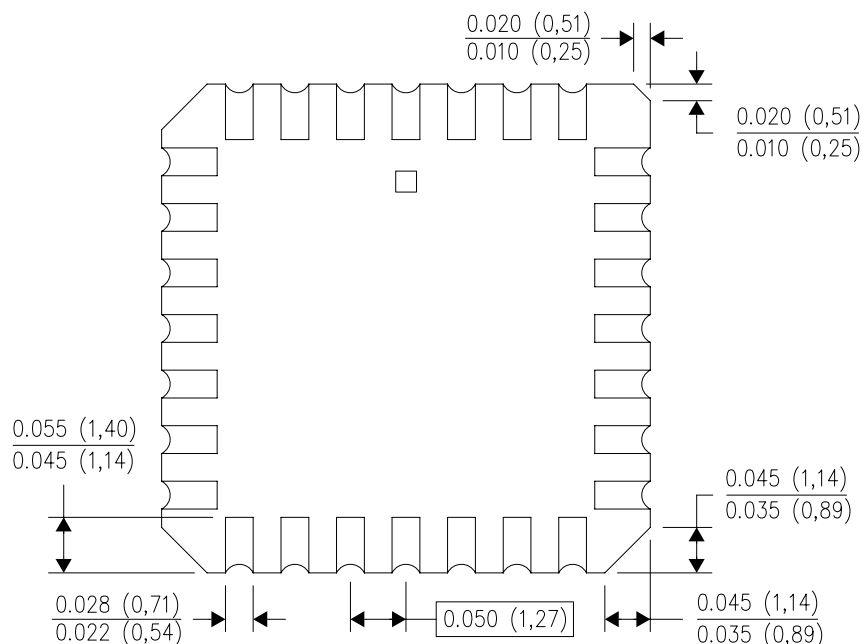
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



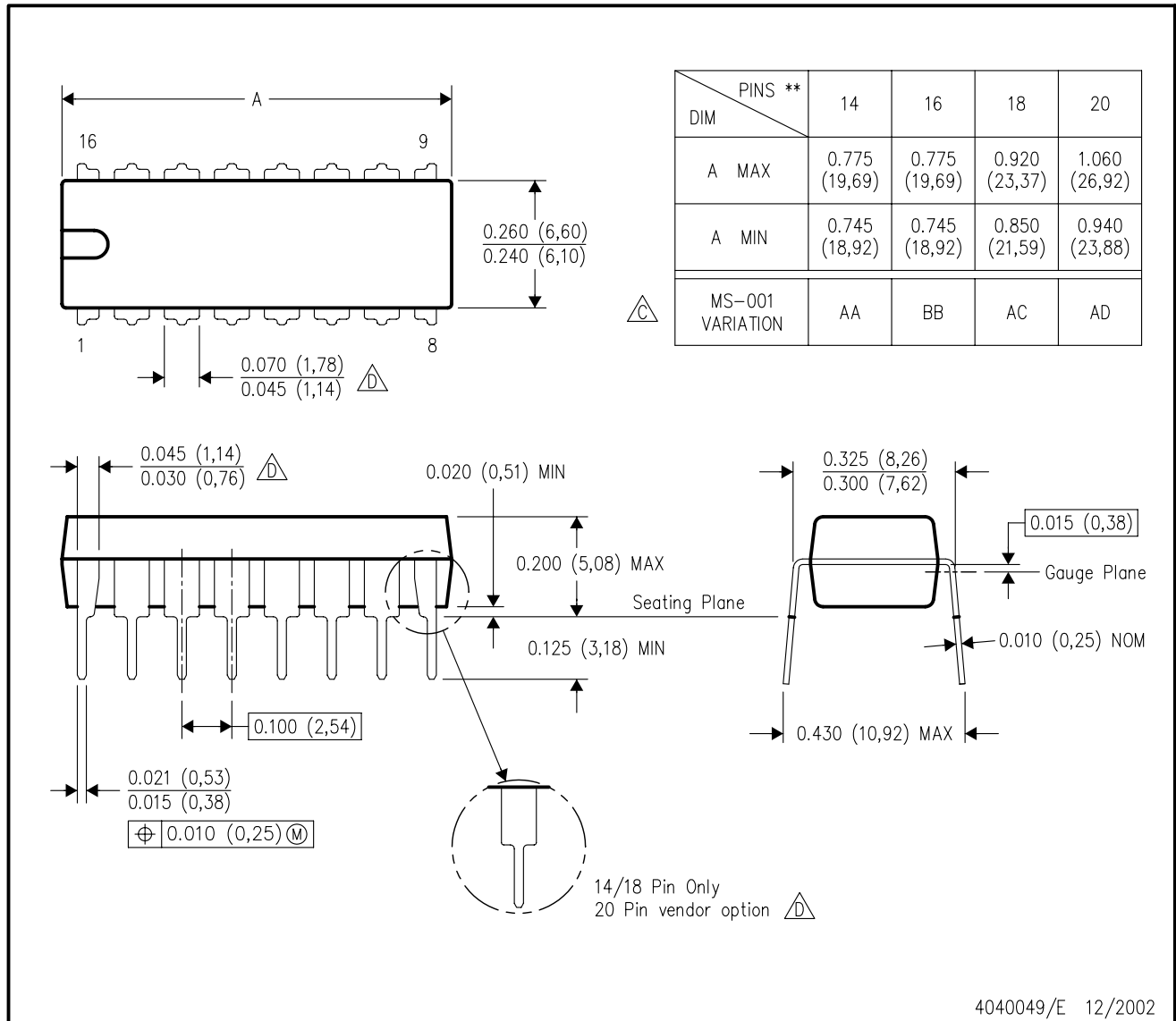
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

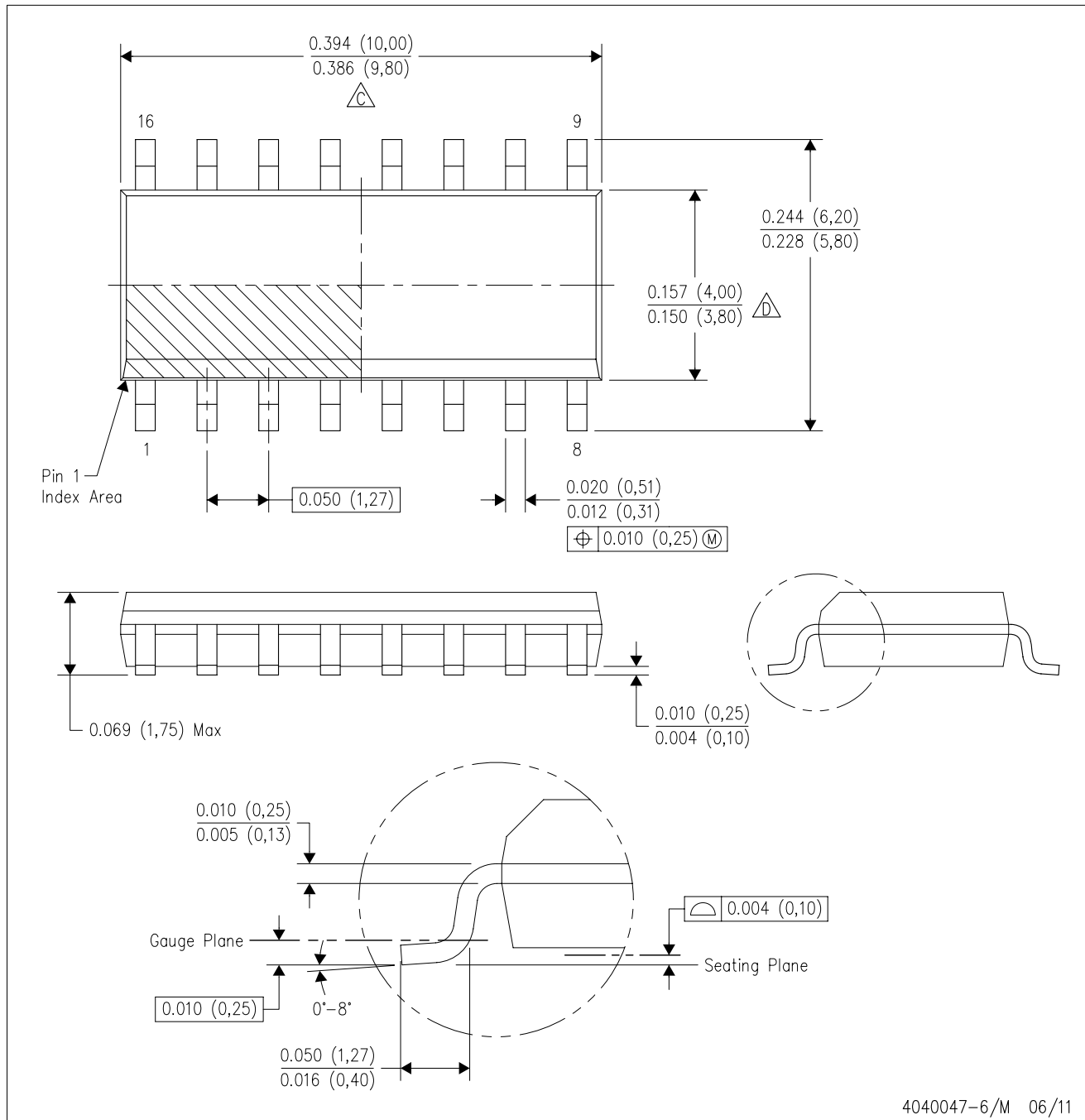
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



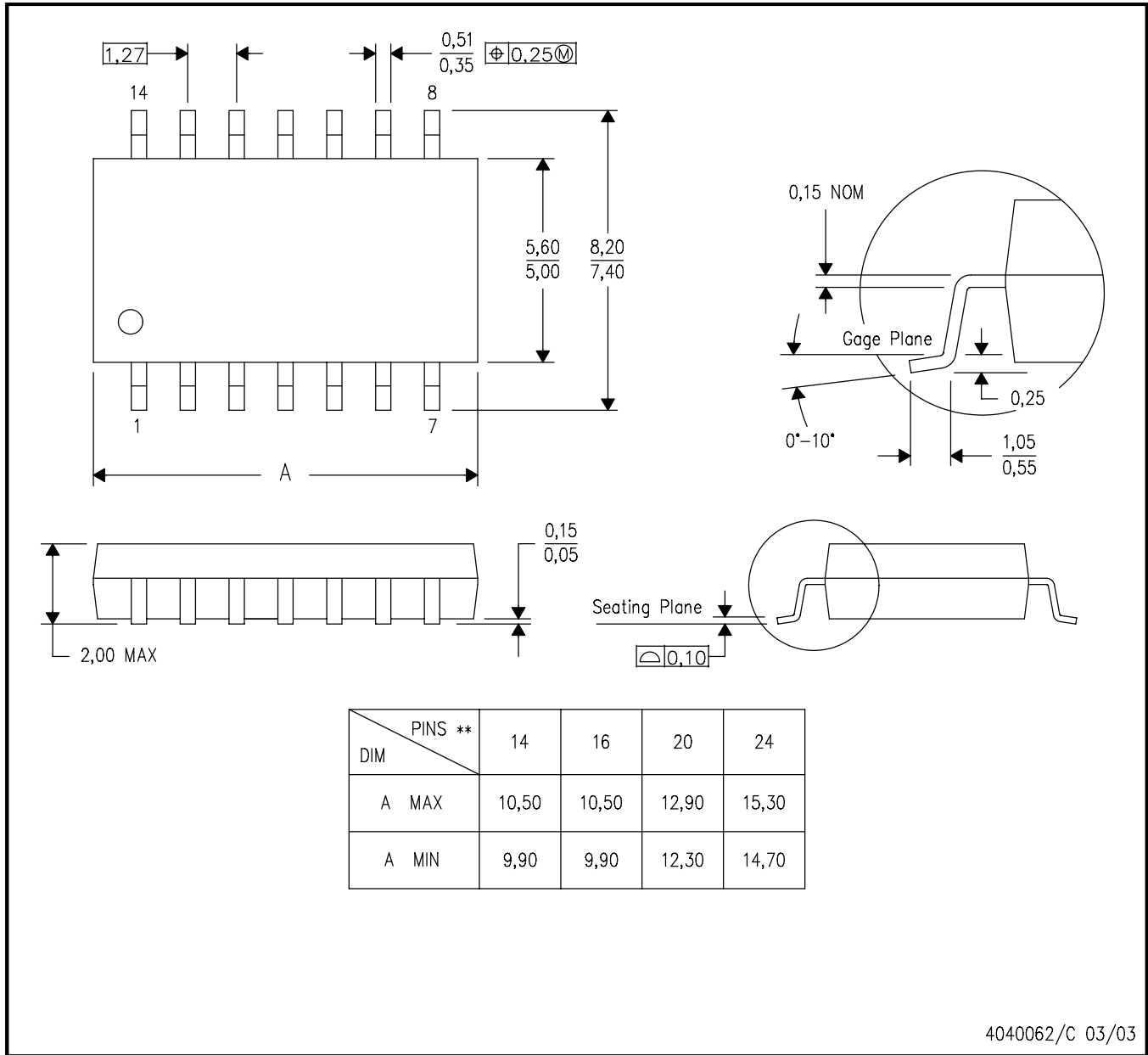
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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